## ATTY. DOCKET NO. SERIAL NO. 10191/3283 Net yer assigned INFORMATION DISCLOSURE APPLICANT(s) STATEMENT BY APPLICANTS **PTO FORM 1449** Wilhelm FREY et al. FILING DATE **GROUP** Herewith Not yet assigned

## U. S. PATENT DOCUMENTS

EXAMINER INITIAL	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE
N	6,210,988	April 3, 2001	Howe et al.	Fig. William St. St. St. St.		

## **FOREIGN PATENT DOCUMENTS**

EXAMINER	DOCUMENT					TRANSI	LATION
INITIAL	NUMBER	DATE	COUNTRY	CLASS	SUB- CLASS	YES	NO
TL	38 74 411*	October 15, 1992	Fed. Rep. of Germany	-		Abs.	
1	0 292 057**	November 23, 1988	Europe	<u>-</u>		Abs.	

## OTHER DOCUMENTS

EXAMINER INITIAL	AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
R	Franke et al., "Post-CMOS Modular Integration of Poly-SiGe Microstructures Using Poly-Ge Sacraficial Layers", Solid- State Sensor and Actuator Workshop, Hilton Head, SC, June 2000, pp. 18-21

EXAMINER Thank	DATE CONSIDERED			
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.				

<sup>\*</sup>Described in Specification

\*\* Corresponds to German Patent No. 38 74 411.